

Title (en)

METHOD OF PRODUCING A CONTACTLESS MICROELECTRONIC DEVICE, SUCH AS FOR AN ELECTRONIC PASSPORT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER KONTAKTLOSEN MIKROELEKTRONISCHEN EINRICHTUNG, ZUM BEISPIEL FÜR EINEN ELEKTRONISCHEN PASS

Title (fr)

PROCEDE DE FABRICATION D'UN DISPOSITIF MICRO-ELECTRONIQUE A FONCTIONNEMENT SANS CONTACT, NOTAMMENT POUR PASSEPORT ELECTRONIQUE

Publication

EP 1846875 A1 20071024 (FR)

Application

EP 06709260 A 20060203

Priority

- FR 2006000271 W 20060203
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Abstract (en)

[origin: WO2006084984A1] The invention relates to a method of producing a contactless microelectronic device, such as for an electronic passport. The inventive method comprises the following steps consisting in: forming an antenna (27) on a thin, flexible substrate (21); placing a perforated sheet (22) comprising at least one cavity (23) in the thickness thereof on the aforementioned substrate (21); depositing a microelectronic chip (24) in each cavity (23) in the perforated sheet (22) and electrically connecting the output studs (25) of the microelectronic chip to the corresponding terminals (26) of the antenna (27); and protecting the microelectronic chip (24) thus wired by sealing the cavity (23) housing the chip. The method is characterised in that the thin, flexible substrate (21) and the perforated sheet (22) each have a thin, calibrated, essentially-uniform and flat thickness, the sum of the thicknesses thereof being less than approximately 350 micrometers and the thickness of the perforated sheet (22) being constant and slightly greater than the thickness of the microelectronic chip (24). In this way, the end product produced is perfectly flat and free of blisters.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2006084984A1

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